

**Amendment to the Specification:**

Please replace the paragraph [0036] of the specification with the following rewritten paragraph:

[0036] FIG. 7 shows an electrical schematic of the discharge path of the IC 400 within the electronic device 600 of FIG. 6 during CDM ESD testing, according to an embodiment of the invention. The charge 702 initially placed on the IC 400 during the beginning of testing is indicated by the letter Q. The capacitance 704 represents the internal, or parasitic, capacitance of the IC 400, such as of the primary substrate 402 of the IC 400. The capacitance 705 represents the capacitance resulting from the capacitive coating 406. That is, the capacitance 705 represents the capacitance resulting from the capacitor effectively made up of the primary substrate 402, the capacitive, or dielectric, coating 406, and the lead frame 602. The resistance 706 represents the internal, or parasitic, ~~capacitance~~ resistance of the IC 400, such as of the primary substrate 402 of the IC 400.